

## High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology



### DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY1850 is an infrared, 850 nm emitting diode based on GaAlAs surface emitter chip technology with high radiant intensity, high optical power and high speed, molded in clear, untinted 0805 plastic package for surface mounting (SMD).

### FEATURES

- Package type: surface mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- Peak wavelength:  $\lambda_p = 850$  nm
- High reliability
- High radiant power
- High radiant intensity
- High speed
- Angle of half sensitivity:  $\phi = \pm 60^\circ$
- Suitable for high pulse current operation
- 0805 standard surface-mountable package
- Floor life: 168 h, MSL 3, according to J-STD-020
- Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR touch panels
- IR Flash
- IR illumination
- 3D TV

### PRODUCT SUMMARY

COMPONENT	$I_e$ (mW/sr)	$\phi$ (deg)	$\lambda_p$ (nm)	$t_r$ (ns)
VSMY1850	10	$\pm 60$	850	10

#### Note

- Test conditions see table "Basic Characteristics"

### ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY1850	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

#### Note

- MOQ: minimum order quantity



ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		$V_R$	5	V
Forward current		$I_F$	100	mA
Peak forward current	$t_p/T = 0.5$ , $t_p = 100\text{ }\mu\text{s}$	$I_{FM}$	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	$I_{FSM}$	1	A
Power dissipation		$P_V$	190	mW
Junction temperature		$T_j$	100	$^{\circ}\text{C}$
Operating temperature range		$T_{amb}$	-40 to +85	$^{\circ}\text{C}$
Storage temperature range		$T_{stg}$	-40 to +100	$^{\circ}\text{C}$
Soldering temperature	According to Fig. 7, J-STD-020	$T_{sd}$	260	$^{\circ}\text{C}$
Thermal resistance junction / ambient	JESD 51	$R_{thJA}$	270	K/W

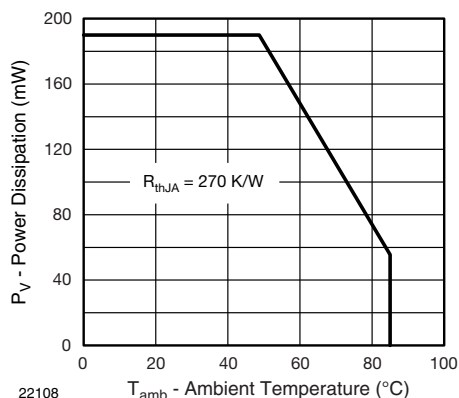


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

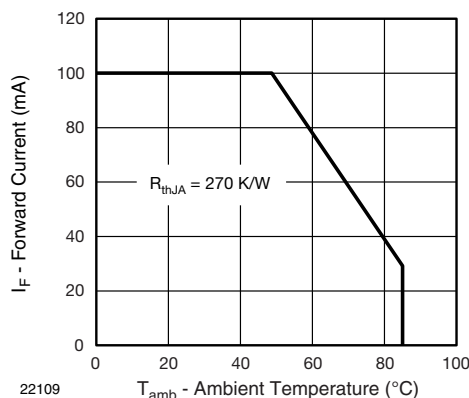


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$V_F$	-	1.65	1.9	V
	$I_F = 1\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$	$V_F$	-	2.9	-	V
Temperature coefficient of $V_F$	$I_F = 1\text{ mA}$	$TK_{VF}$	-	-1.4	-	mV/K
	$I_F = 10\text{ mA}$	$TK_{VF}$	-	-1.18	-	mV/K
Reverse current		$I_R$	Not designed for reverse operation			$\mu\text{A}$
Junction capacitance	$V_R = 0\text{ V}$ , $f = 1\text{ MHz}$ , $E = 0\text{ mW/cm}^2$	$C_J$	-	125	-	pF
Radiant intensity	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$I_e$	5	10	15	mW/sr
	$I_F = 1\text{ A}$ , $t_p = 100\text{ }\mu\text{s}$	$I_e$	-	85	-	mW/sr
Radiant power	$I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$	$\phi_e$	-	50	-	mW
Temperature coefficient of radiant power	$I_F = 100\text{ mA}$	$TK_{\phi_e}$	-	-0.35	-	%/K
Angle of half intensity		$\phi$	-	$\pm 60$	-	deg
Peak wavelength	$I_F = 100\text{ mA}$	$\lambda_p$	840	850	870	nm
Spectral bandwidth	$I_F = 30\text{ mA}$	$\Delta\lambda$	-	30	-	nm
Temperature coefficient of $\lambda_p$	$I_F = 30\text{ mA}$	$TK_{\lambda_p}$	-	0.25	-	nm/K
Rise time	$I_F = 100\text{ mA}$ , 20 % to 80 %	$t_r$	-	10	-	ns
Fall time	$I_F = 100\text{ mA}$ , 20 % to 80 %	$t_f$	-	10	-	ns
Virtual source diameter		$d$	-	0.5	-	mm

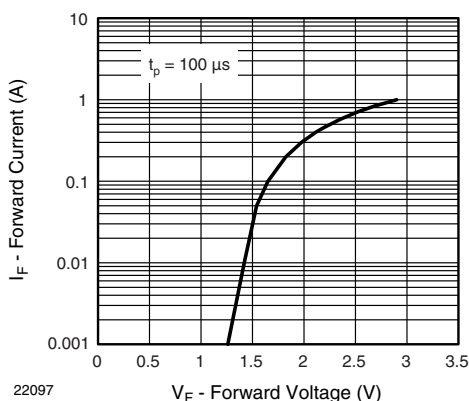
**BASIC CHARACTERISTICS** ( $T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified)


Fig. 3 - Forward Current vs. Forward Voltage

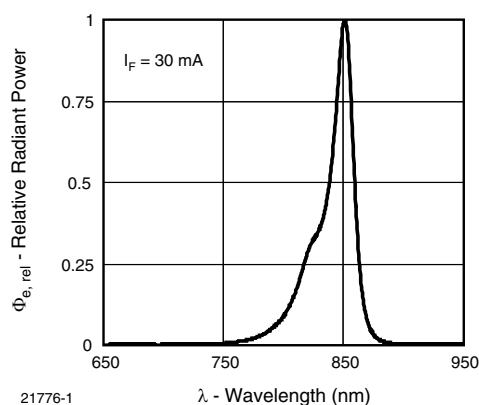


Fig. 5 - Relative Radiant Power vs. Wavelength

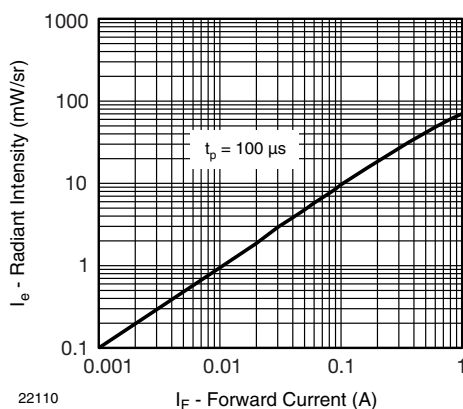


Fig. 4 - Radiant Intensity vs. Forward Current

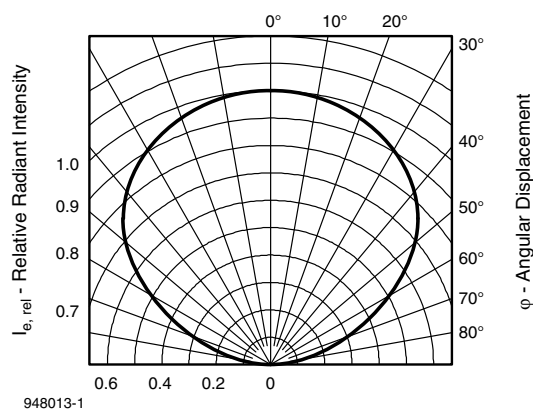


Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

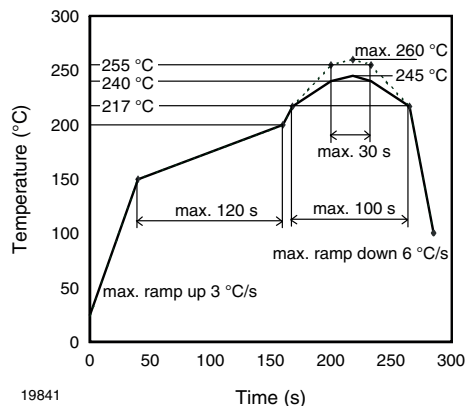
**REFLOW SOLDER PROFILE**


Fig. 7 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020

**DRYPACK**

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

**FLOOR LIFE**

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

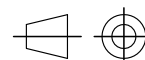
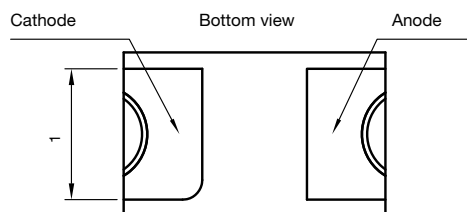
Moisture sensitivity: level 3

Floor life: 168 h

Conditions:  $T_{amb} < 30\text{ }^{\circ}\text{C}$ , RH < 60 %

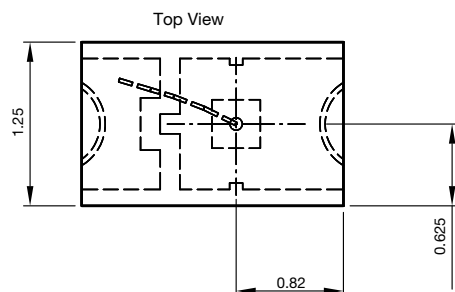
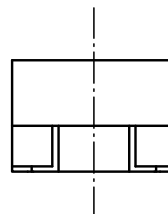
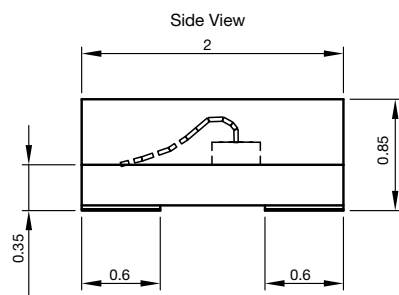
**DRYING**

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at  $40\text{ }^{\circ}\text{C}$  (+ 5 °C), RH < 5 %.

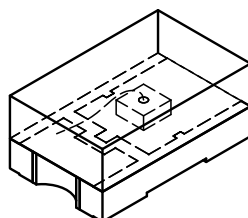
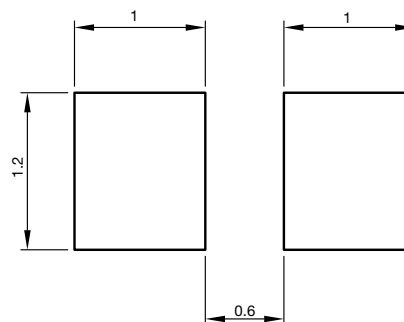
**PACKAGE DIMENSIONS** in millimeters


technical drawings  
specifications  
according to DIN

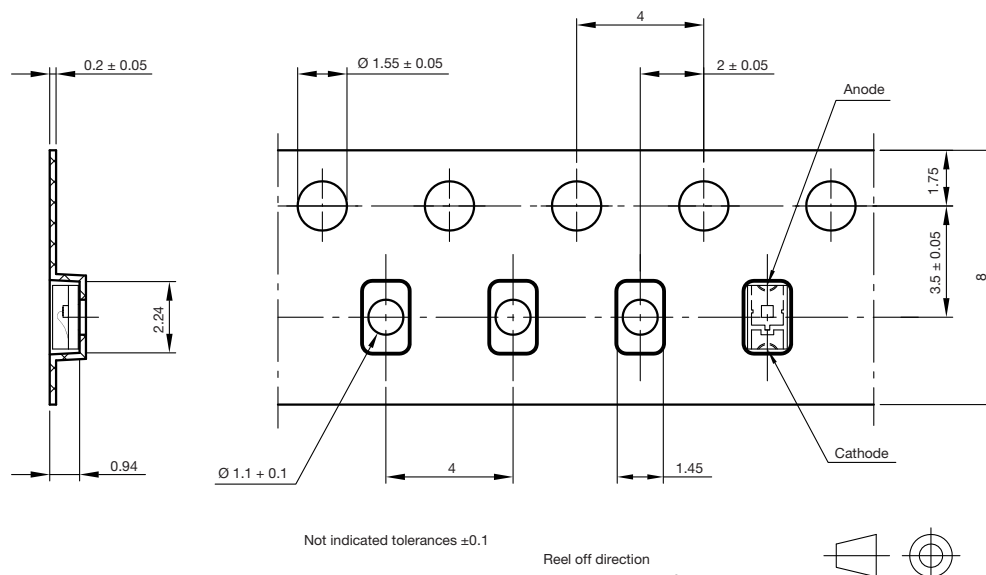
Not indicated tolerances  $\pm 0.1$



Recommended solder pad  
footprint



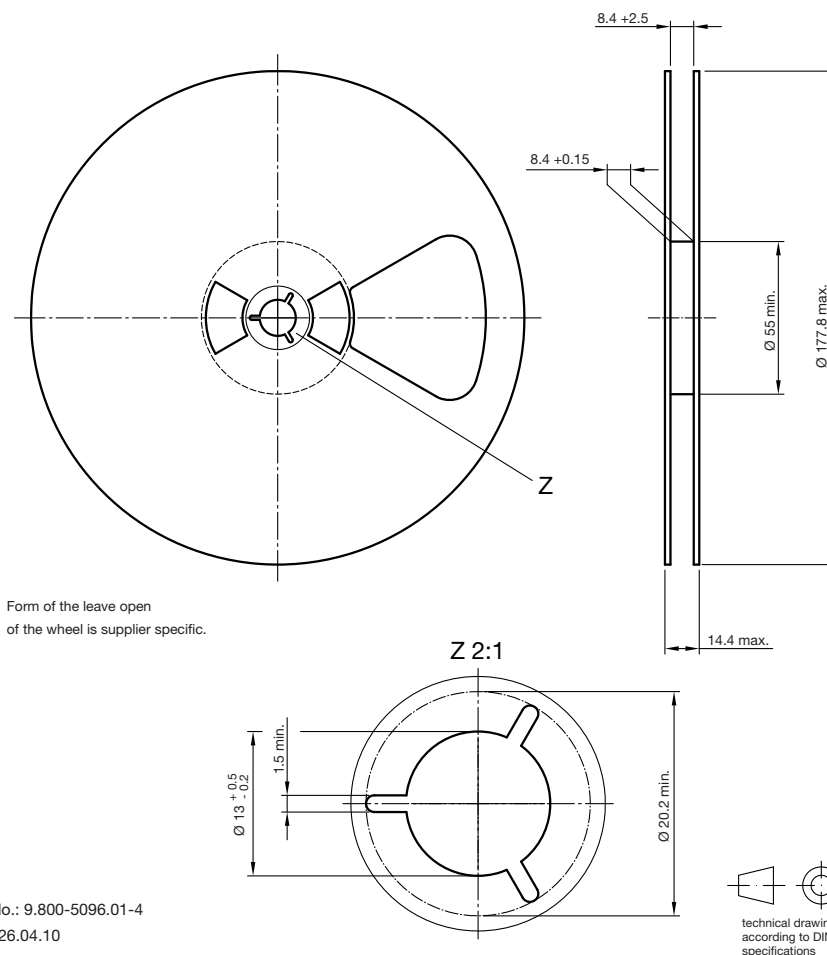
Drawing-No.: 6.541-5083.01-4  
Issue: 2; 10.09.2013

**BLISTER TAPE DIMENSIONS** in millimeters


Drawing-No.: 9.700-5352.01-4

Issue: 1; 13.04.10

22112

**REEL DIMENSIONS** in millimeters


Drawing-No.: 9.800-5096.01-4

Issue: 2; 26.04.10

20875



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